



## Product Change Notification / BLAS-28XZGK309

---

### Date:

13-May-2024

### Product Category:

8-Bit Microcontrollers

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 6736 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

### Affected CPNs:

[BLAS-28XZGK309\\_Affected\\_CPN\\_05132024.pdf](#)

[BLAS-28XZGK309\\_Affected\\_CPN\\_05132024.csv](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

### Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material	Au	Au	CuPdAu
Die Attach Material	3280	3280	3280
Molding Compound Material	G700LTD	G700LTD	G700LTD
Lead-Frame Material	C194	C194	C194

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve productivity and on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material at MP3A assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**June 7, 2024 (date code: 2423)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	February 2024					>	May 2024					June 2024				
Workweek	05	06	07	08	09		18	19	20	21	22	23	24	25	26	27
Initial PCN Issue Date	x															
Qual Report Availability									x							
Final PCN Issue Date									x							
Estimated Implementation Date												x				

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**February 01, 2024: Issued initial notification.

May 13, 2024: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 7, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_BLAS-28XZGK309\\_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.